ATTY DOCKET NO.: Q75814

AMENDMENT UNDER 37 C.F.R. § 1.114(c)

U.S. APPLN. NO.: 10/632,919

AMENDMENTS "O THE CLAIMS

This listing:of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1 (currently amended): A compression bonding method in which an element is bended to a substrate, the method comprising:

forming a laver having metal on at least a part of a surface of the substrate;

disposing the element on the layer; and

bonding the element to the layer by applying pressure on the element toward the layer and irradiating light to which the element is transparent, on a bonding area between the element and the layer, The method of claim 11, wherein the light provides activating energy which allows an interactio a between the layer and the element approximately at room temperature.

- 2 (currently amended): The method of claim-111, wherein the element is formed of silica glass.
- 3 (currently amended): The method of claim-111, wherein the substrate is a silicon substrate.
- 4. (currently amended):—A compression bonding method in which an element is bonded to a substrate, the method comprising:

forming a layer having metal on at least a part of a surface of the substrate;

disposing the element on the layer; and

AMENDMENT UNDER 37 C.F.R. § 1.114(c)

ATTY DOCKET NO.: Q75814

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bonding the element to the layer by applying pressure on the element toward the layer and irradiating light to which the element is transparent, on a bonding area between the element and the layer The nethod of claim 11, wherein the light is irradiated on the bonding area for a predetermined time after the application of pressure.

- 5 (can eled).
- 6 (currently amended): The method of claim—1_11, wherein the light has a wavelength of not less than approximately 180 nm.
- 7 (currently amended): The method of claim-111, wherein the pressure, which acts at an interface between the layer and the element, ruptures a native oxide film on the layer and allows the element 10 contact a non-oxidized element of the layer.
 - 8 (canceled).
- 9. (currently amended): The method of claim-8_11, wherein a cross section of the element is round.
- 10. (currently amended): The method of claim-8_11, wherein the element is an optical element that is one cf a lens, an optical fiber, and a prism.

AMENDMENT UNDER 37 C.F.R. § 1.114(c) U.S. APPLN. NO.: 10/632,919

(c) ATTY DOCKET NO.: Q75814

11. (previously presented): A compression bonding method in which an element is

bonded to a substrate, the method comprising:

forming a layer having metal on at least a part of a surface of the substrate;

disposing the element on the layer; and

bonding the element to the layer by applying pressure on the element toward the layer

and irradiating light to which the element is transparent, on a bonding area between the element

and the layer, wherein the layer is a discontinuous layer.

12. (original): The method of claim 11, wherein the layer is formed as strips or dots.

13. (original): The method of claim 11, wherein a surface of the element which

contacts the layer is substantially flat.

14-20 (canceled).

21. (currently amended): A compression bonding method in which an element is

bonded to a substrate, the method comprising:

forming a lawer having metal on at least a part of a surface of the substrate;

disposing the cloment on the layer; and

bonding the clement to the layer by applying pressure on the element toward the layer

and irradiating light to which the element is transparent, on a bonding area between the element

and the layer The piethod of claim 11, wherein the light is substantially in the UV wavelength

range.

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AMENDMENT UNDER 37 C.F.R. § 1.114(c) U.S. APPLN, NO.: 10/632,919

ATTY DOCKET NO.: Q75814

22-24 (canceled).

- 25. (currently amended): The method of claim—1_11, wherein the metal includes aluminum.
- 26. (previously presented): The method of claim 7, wherein the non-oxidized element is aluminum.
 - 27. (canceled).